# SUPER HIGH DENSITY MODULE WITH INTEGRATED WAFER LEVEL PACKAGES

## FIELD OF THE INVENTION

This invention relates generally to integrated circuit chip packages, and more specifically to a method of forming an integrated circuit package at a wafer level.

## BACKGROUND OF THE INVENTION

With the increase in memory needed by software, the trend in state-of-the-art microprocessors is toward higher performance, high-density memory modules, such as single in-line memory modules (SIMMs) or dual in-line memory modules (DIMMs), which are circuit cards with memory chips attached. Having higher capacity memory chip units or packing more memory chip units on a memory module is one way to increase memory density on a module.

Conventional methods of mounting multiple die units on a module is through stacking the die units or attaching a daughter board to the main module board. However, a profusion of small electronic products such as pages and cellular telephones demand small product size and low profile products. The demand by consumers for miniature electronic devices has increased the need for powerful yet compact, ultra-thin semiconductor devices.

Based on these and other needs and deficiencies, an improved die package for achieving a high density memory module would be desirable.

## SUMMARY OF THE INVENTION

The present invention provides a wafer level semiconductor die package, a semiconductor wafer comprising one or more wafer level packages, an electronic system comprising an integrated circuit module that includes one or more of the wafer level packages, a memory module comprising a printed circuit board and an integrated circuit module that includes at least one of the wafer level packages, and methods of fabricating the

die packages on a wafer level, and integrated circuit modules that include one or more packages.

In one aspect, the invention provides a die package. In one embodiment, the die package comprises a redistribution layer interconnecting two or more dies disposed on a substrate, typically a semiconductor wafer, the redistribution layer comprising a first trace connecting a bond pad of each of two dies, and a second trace connecting one of the bond pads of the two dies to a ball pad. The die package can further include an insulating layer disposed over the traces, and/or a ball contact mounted on the ball pad.

In another embodiment, the die package is an integrated wafer level package comprising a plurality of electrically conductive traces disposed on an insulating film overlying two or more dies disposed on a semiconductor wafer or other substrate, each die comprising one or more bond pads, and each of the bond pads exposed through an opening in the insulating film; a redistribution layer comprising a plurality of traces and ball pads disposed on the insulating film, and a first trace of the redistribution layer interconnecting a bond pad of a first die to the bond pad of a second die, and a second trace connecting one of said bond pads to a ball pad disposed on the insulating film. Thus, a trace connects each bond pad of the dies to either a ball pad or to the bond pad of another die which bond pad is connected by a trace to a ball pad.

In another embodiment, the die package comprises an integrated wafer level package, comprising a support substrate, typically a semiconductor wafer, comprising at least three semiconductor dies, each die comprising a plurality of bond pads; an insulating film disposed over the dies with openings exposing the bond pads of the dies; a plurality of traces and ball pads disposed on the insulating film; a bond pad of each of a first die and second die interconnected by a trace, and one of said bond pads of the first and second dies connected by a trace to a ball pad; an insulating layer disposed over the traces; and a plurality of traces disposed on the insulating layer, including a trace connecting a bond pad of either the first die or the second die to a bond pad of a third die.

In yet another embodiment, the die package comprises an integrated wafer level package, comprising a semiconductor wafer or other support substrate comprising three or

more semiconductor dies, each die comprising one or more bond pads, and a first redistribution layer including a trace interconnecting a bond pad of each of a first die and a second die; an insulating layer disposed over the first redistribution layer and comprising openings exposing the bond pads of the dies; and a second redistribution layer comprising a plurality of traces disposed on the insulating layer;, including a trace interconnecting a bond pad of either the first die or the second die to a bond pad of a third die; wherein one of the bond pads of the first, second or third dies is connected by a trace to a ball pad within the package. The first redistribution layer can be disposed on an insulating film overlying the dies. The ball pad can be part of the first redistribution layer and connected by a trace to one of the bond pads of the first and second dies, or part of the second redistribution layer with a trace of the second redistribution layer connecting the bond pad of any of the first, second or third dies to the ball pad.

In yet another embodiment, the die package comprises an integrated wafer level package, comprising a semiconductor wafer or other support substrate comprising two or more dies, each die comprising a plurality of bond pads; an insulating film disposed over the dies, the film comprising openings aligned with and exposing the bond pads of the dies; a first redistribution layer disposed on the insulating film and including a trace interconnecting a bond pad of each of a first die and a second die; a first insulating layer disposed over the first redistribution layer and comprising openings exposing at least one of the first traces; a second insulating layer disposed over the first insulating layer and comprising openings exposing the first trace(s) and openings for ball pads; and a second redistribution layer comprising a ball pad and a trace disposed on the second insulating layer, and a via interconnect disposed in the opening onto the first trace, the second trace connecting the via interconnect to the ball pad.

In another aspect, the invention provides a semiconductor wafer. In various embodiments, the wafer comprises one or more wafer level packages according to the invention.

In another aspect, the invention provides an electronic system comprising an integrated circuit module comprising at least one wafer level package according to the

invention. In one embodiment the integrated circuit module comprises a multi-chip module, such as a DIMM board, among others.

In yet another aspect, the invention provides a memory module comprising a printed circuit board and an integrated circuit module comprising at least one wafer level package according to the invention. In one embodiment, the memory module can comprise an integrated circuit module in the form of a DIMM board or other multi-chip module.

In a further aspect, the invention provides methods of fabricating the foregoing die packages on a wafer level. In an embodiment of a method of fabricating a die package on a wafer level, the method comprises forming a redistribution layer over at least two dies disposed on a semiconductor wafer or other support substrate, the redistribution layer comprising a plurality of traces and one or more ball pads including a trace connecting a bond pad of each of a first and second die, and a trace connecting one of the bond pads to a ball pad.

In another embodiment of a method of fabricating a wafer level die package, the method comprises providing a substrate having a plurality of semiconductor dies formed thereon, each die comprising one or more bond pads; applying an insulating film over the substrate; forming openings through the insulating film to the bond pads of the dies; and forming a redistribution layer over the insulating film, the redistribution layer comprising a plurality of traces and ball pads, including a trace interconnecting a bond pad of each of a first die and a second die, and a trace connecting one of the bond pads of the first and second dies to a ball pad. The method can further include steps of applying an insulating layer over the redistribution layer and forming openings through the insulating layer to the ball pads, and mounting a ball contact on each of the ball pads. In another embodiment, the insulating layer can be applied over the redistribution layer and openings formed to the bond pads and ball pads, and a second redistribution comprising a plurality of traces can be formed over the insulating layer, including a trace interconnecting a bond pad of either the first die or the second die to a bond pad of a third die.

In yet another embodiment of a method of fabricating a die package on a wafer level, the method comprises forming a first redistribution layer over a plurality of dies disposed on

a semiconductor wafer or other substrate, including a trace interconnecting a bond pad of each of a first die and a second die; applying an insulating layer over the traces which includes openings to the bond pads of the dies; and forming a second redistribution layer comprising a plurality of traces and ball pads over the insulating layer, including a trace interconnecting a bond pad of either the first or the second die to a bond pad of a third die; wherein a trace of either the first or second redistribution layers connects one of said bond pads of the first, second or third dies to a ball pad. The ball pad can be provided as part of the first redistribution layer formed on an insulating film overlying the dies whereby the ball pad is connected by a trace to one of the interconnected bond pads of the first or second dies. In another embodiment, the ball pad can be provided as part of the second redistribution layer, connected by a trace to one of the interconnected bond pads of the first, second or third dies.

In yet another embodiment of a method of fabricating a die package on a wafer level, the method comprises forming a first redistribution layer over at least two dies disposed on a substrate, the first redistribution layer comprising a plurality of traces including a trace connecting a bond pad of each of the two dies; forming an insulating layer over the first redistribution layer; forming openings through the insulating layer to expose each of the traces of the first redistribution layer; and forming a second redistribution layer over the insulating layer, the second redistribution layer comprising a plurality of ball pads and traces, and a via interconnect disposed in each of the openings of the insulating layer in contact with the trace of the first RDL, the trace of the second RDL connecting the via interconnect to at least one ball pad. The method can further comprise the steps of forming an insulating layer over the second redistribution layer; forming openings to expose the ball pads; and connecting ball contacts to the ball pads of the second redistribution layer; and further singulating the wafer to form individual packages, each package comprising the first and second dies connected by the traces of the first redistribution layer.

In another aspect, the invention provides methods for fabricating an integrated circuit module. In one embodiment, the method comprises the steps of providing a substrate comprising a plurality of wafer level packages according to the invention; separating each

package on the substrate to form individual packages; and assembling one or more packages into an integrated circuit module, for example, a multi-chip module such as a DIMM board.

The present invention provides a multiple die package having an exceptionally high memory capacity with a low profile. The die package achieves a single unit (die package) having an increased memory capacity using current memory chips by virtue the interconnections between two or more chips within the package, without having to wait for the availability of the next higher density chip. The integrated wafer package also has the advantage of space saving on a module board due to the compact and thin profile, which in turn allows more integrated units/packages and higher memory capacity on the flip chip memory module such as a SIMM or DIMM board. The die package also provides superior signal integrity.

The configuration of the RDL with traces connecting bond pads of two or more dies together and routing the connection to a single ball pad also eliminates the need for a separate pin or ball contact for each individual bond pad, resulting in a lower pin count compared to other memory module chip units. The package also is easier to lay out on a DIMM board or or other memory module since part of the routing is done on a wafer level.

## BRIEF DESCRIPTION OF THE DRAWINGS

Preferred embodiments of the invention are described below with reference to the following accompanying drawings, which are for illustrative purposes only. Throughout the following views, the reference numerals will be used in the drawings, and the same reference numerals will be used throughout the several views and in the description to indicate same or like parts.

**FIG. 1** is a plan view of a substrate containing wafer level packages according to the invention.

**FIG. 2** is a perspective view of an embodiment of a wafer level package according to the invention, showing an insulating layer partially cut away to expose a redistribution layer.

**FIG. 3** is a plan view of the wafer level package of **FIG. 2**, without an insulating layer.

**FIG. 4** is a cross-sectional, side elevational view of the wafer level package of **FIG. 3**, taken along line 4-4.

**FIG. 5** is a plan view of another embodiment of a wafer level package according to the invention.

**FIG. 6** is a partial view of the wafer level package of **FIG. 3**, showing a portion of the redistribution layer.

**FIG. 7** is a plan view of a processing step in the fabrication of the wafer level package of **FIG. 2**, according to an embodiment of a method of the invention showing the bond pads exposed through openings in the insulating film.

**FIG. 8** is a cross-sectional view of the package of **FIG. 7**, taken along line 8-8.

**FIG. 9** is a partial cross-sectional view of the wafer level package of **FIG. 4**, showing an embodiment of a multi-layered RDL.

**FIG. 10** is a plan view of a processing step in the fabrication of the wafer level package of **FIG. 2**, in which an insulating layer, shown as partially cut away, is applied over the RDL layer, and ball contacts are mounted on the ball pads.

**FIG. 11** is a cross-sectional view of the package of **FIG. 10**, taken along line 11-11.

**FIGS. 12-17** illustrate sequential processing steps in the fabrication of another embodiment of a wafer level package according to the invention.

**FIG.12** is a plan view of a processing step in which an insulating layer, shown as partially cut away, is applied over the RDL of the package depicted in **FIG. 3**, and openings are formed to the bond pads and ball pads.

**FIG. 13** is a cross-sectional, side elevational view of the wafer level package of **FIG. 12**, taken along line 13-13.

**FIG. 14** is a plan view of a subsequent processing step in which a second redistribution layer (RDL) is fabricated on the insulating layer, shown as partially cut away.

**FIG. 15** is a cross-sectional, side elevational view of the wafer level package of **FIG. 14**, taken along line 15-15.

**FIG. 16** is a plan view of a subsequent processing step in which an insulating layer is applied over the second RDL of the package depicted in **FIG. 14**, with ball contacts mounted on the ball pads of the dies.

**FIG. 17** is a cross-sectional, side elevational view of the wafer level package of **FIG. 16**, taken along line 17-17.

**FIG. 18** is a plan view of another embodiment of a wafer level package according to the invention, having a second redistribution layer disposed on a partially cut-away insulating layer overlying a first distribution layer.

**FIGS. 19-27** illustrate sequential processing steps in the fabrication of another embodiment of a wafer level package according to the invention.

**FIG. 19** is a plan view of a processing step in which a redistribution layer (RDL) is formed to connect bond pads of the dies of the package.

**FIG. 20** is a cross-sectional, side elevational view of the wafer level package of **FIG. 19**, taken along line 20-20.

**FIG. 21** is a plan view of a subsequent processing step in which an insulating layer, shown as partially cut away, is applied over the RDL of the package depicted in **FIG. 19**, and openings are formed to the bond pads of the dies.

**FIG. 22** is a cross-sectional, side elevational view of the wafer level package of **FIG. 21**, taken along line 22-22.

**FIG. 23** is a plan view of a subsequent processing step in which a second redistribution layer (RDL) is fabricated on the insulating layer, shown as partially cut away.

**FIG. 24** is a cross-sectional, side elevational view of the wafer level package of **FIG. 23**, taken along line 24-24.

**FIG. 25** is a partial view of the package of **FIG. 23**, showing a schematic depiction of trace connections of bond pads of the dies, with traces of the first RDL shown as broken lines.

**FIG. 26** is a plan view of a subsequent processing step in which an insulating layer is applied over the second RDL of the package depicted in **FIG. 24**, with ball contacts mounted on the ball pads of the dies.

**FIG. 27** is a cross-sectional, side elevational view of the wafer level package of **FIG. 26**, taken along line 27-27.

**FIGS. 28-36** illustrate sequential processing steps in the fabrication of another embodiment of a wafer level package according to the invention.

**FIG. 28** is a plan view of a processing step in which a first redistribution layer (RDL) is formed to connect bond pads of the dies of the package.

**FIG. 29** is a cross-sectional, side elevational view of the wafer level package of **FIG. 28**, taken along line 29-29.

**FIG. 30** is a plan view of a subsequent processing step in which a first insulating layer, shown as partially cut away, is applied over the first RDL of the package depicted in **FIG. 28**, and openings are formed to the interconnecting traces.

**FIG. 31** is a cross-sectional, side elevational view of the wafer level package of **FIG. 30**, taken along line 31-31.

**FIG. 32** is a plan view of a subsequent processing step in which a second insulating layer, shown as partially cut away, is applied over the first insulating layer of the package depicted in **FIG. 30**, with openings formed to the interconnecting traces, and a second redistribution layer (RDL) is fabricated on the second insulating layer to provide via interconnects to the interconnecting traces within the openings, and ball pads and traces connecting the via interconnects to the ball pads.

**FIG. 33** is a cross-sectional, side elevational view of the wafer level package of **FIG. 32**, taken along line 33-33.

**FIG. 34** is a cross-sectional, side elevational view of the wafer level package of **FIG. 32**, taken along line 34-34.

**FIG. 35** is a plan view of a subsequent processing step in which an insulating layer, shown as partially cut away, is applied over the second RDL of the package depicted in **FIG. 32**, with openings formed to the ball pads, and ball contacts mounted on the ball pads of the dies.

**FIG. 36** is a cross-sectional, side elevational view of the wafer level package of **FIG. 35**, taken along line 36-36.

**FIG. 37** is a block diagram of a memory module incorporating a plurality of wafer level packages.

## DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

The invention will be described generally with reference to the drawings for the purpose of illustrating embodiments only and not for purposes of limiting the same. The figures illustrate processing steps for use in fabricating semiconductor devices in accordance with the present invention. It should be readily apparent that the processing steps are only a portion of the entire fabrication process.

In the current application, the terms "semiconductive wafer fragment" or "wafer fragment" or "wafer" will be understood to mean any construction comprising semiconductor material, including but not limited to bulk semiconductive materials such as a semiconductor wafer (either alone or in assemblies comprising other materials thereon), and semiconductive material layers (either alone or in assemblies comprising other materials). The term "substrate" refers to any supporting structure including, but not limited to, the semiconductive wafer fragments or wafers described above.

The present invention provides a semiconductor die package comprising two or more dies that can be fabricated at the wafer level, that is, an entire wafer of active device dies can be processed according to the invention to form one or more die packages, and burn-in and testing of the one or more packages can be performed before the wafer is separated into individual packages. It is also contemplated that packages can be defined as comprising, multiple, unseparated packages containing two or more dies, or whole or partial wafers.

Referring to **FIGS. 1-4**, a first embodiment of an integrated wafer level package 10 according to the invention is depicted. The wafer level package 10 comprises two or more semiconductor dies. For illustrative purposes, each package 10 includes four dies 12a-12d (delineated by the dashed lines), which is merely exemplary.

The dies are fabricated on a surface of a substrate 14, typically a semiconductor wafer, through etching, deposition, or other well known techniques, and contain integrated circuitry comprising active devices to perform a specific memory function. A dynamic

random access memory circuit is exemplary of such an integrated circuit, although other circuits for any function, such as processors, can be packaged according to the invention. Scribe lines 16 are typically provided between the wafer level packages 10. The active surface 18 of the dies 12a-12d includes a series of bond pads 20a-20d in electrical communication with the integrated circuits contained within each die 12a-12d. In the illustrated example, the bond pads 20a-20d are in a linear pattern in a longitudinal arrangement on each of the dies, although other bond pad arrangements can be utilized. A passivation or insulating (dielectric) film 22 has been formed over the surface of the wafer 14 to passivate the active surface of the dies and to seal the device structures of the dies from contamination and moisture, and as a scratch protection layer. Openings formed in the insulating film align with and expose the bond 20a-20d pads of the dies.

The wafer level package 10 further includes a redistribution layer (RDL) 24 formed on the insulating film 22. The RDL 24 includes electrically conductive traces 26 that connect the bond pads 20a-20d of the dies to ball pads 28 for attaching external ball contacts 30 such as solder balls.

According to the invention, the RDL 24 of the wafer level package 10 also includes traces 32 that interconnect the bond pads of two or more of the dies within the wafer level package. For example, as illustrated in **FIG. 3**, in the embodiment of the wafer level package 10, the traces 32 of the RDL are formed to interconnect the bond pads 20a of a first die 12a to the bond pads 20b of a second die 12b, and the bond pads 20c of a third die 12c to the bond pads 20d of a fourth die 12d. Referring to **FIG. 5**, in another embodiment of a wafer level package 10' according to the invention, the traces 32' of the RDL 24' are patterned to interconnect the bond pads 20a' of a first die 12a' with the bond pads 20c' of a third die 12c', and the bond pads 20b' of a second die 12b' with the bond pads 20d' of a fourth die 12d'. The illustrated trace interconnections are merely exemplary, and other configurations of the trace interconnections 32 can be utilized to interconnect the bond pads of the dies to each other and to the ball pads within the wafer level package.

Each bond pad of a die within the wafer level package is connected to a ball pad 28 either directly through a trace 26, or indirectly through the interconnecting trace 32 leading to

the bond pad of the adjoining die, which is then connected through the trace 26 to the ball pad 28. For example, referring to **FIG. 6**, the bond pad $20b_1$ of die 12b is directly connected to the ball pad 28(b) via the trace 26. As further shown, the bond pad $20a_1$ of die 12a is also connected to the same ball pad 28(b) indirectly through the interconnecting trace 32 and the trace 26 leading from the bond pad $20b_1$ of die 12b.

Referring now to **FIG. 7**, a processing step is illustrated in an embodiment of a method for forming the wafer level package 10 of **FIG. 2**, which comprises four dies 12a-12d. The semiconductor dies 12a-12d are formed on a semiconductor wafer or other substrate 14, through etching, deposition, or other well known techniques in the art, and respectively include bond pads 20a-20d. The bond pads 20a-20d typically comprise a conductive metal or metal alloy such as aluminum, aluminum alloy, titanium, tungsten, titanium-tungsten alloy, tantalum, platinum, copper, or refractory metal silicide, for example, and are electrically connected to the die circuitry.

As also shown in **FIG. 8**, an insulating film 22 can be formed over the surface of the substrate 14 to passivate the active surface of the dies, as known in the art, typically by oxidizing or nitriding to form a silicon dioxide or silicon nitride layer or a combination of the two. The insulating film 22 can also be formed of a dielectric material such as polyimide or another non-conductive elastomer, a photoimageable polymer such as benzocyclobutene (BCB), or a spin on glass (SOG) such as phosphosilicate glass (PSG), borosilicate glass (BSG) and borophosphosilicate glass (BPSG), among other insulating materials. The material can be applied using conventional methods including deposition techniques, spin coating, spraying, flow coating, brush coating, among other application techniques. The insulating film 22 can be masked and etched by conventional methods to form openings 34 that align with and expose the bond pads 20a-20d of the dies 12a-12d.

As illustrated in **FIGS. 3-4**, a redistribution layer (RDL) 24 is formed on the insulating film 22, which includes traces 26, ball pads 28, and interconnecting traces 32.

The present invention utilizes a conductive redistribution wafer level package technology on two or more chips whereby, instead of the redistribution traces confined to a single chip (unit), the routing traces are extended to one or more adjacent chips (units) with

all common signal buses being tied together. The structure of the redistribution layer to interconnect two or more dies within a package increases the memory capacity of the die package. For example, where redistribution traces interconnect two die units, the memory capacity of the combined units is double. This capacity can be extended to additional multiple units, for example, four units, eight units, sixteen units, and so on. The present invention thus results in an increase in the capacity of a singulated unit or die package as a wafer scale (level) package. Further, since address, data and some control buses or even power/ground pins for memory devices are shared, the number of pin-out/contact balls for the integrated package is reduced compared to single die units.

The RDL 24 typically comprises a highly conductive metal or metal alloy such as copper, aluminum, gold, and nickel, for example, or a conductive polymer material. The RDL 24 can be formed using known techniques in the art such as chemical vapor deposition (CVD), plasma enhanced chemical vapor deposition (PECVD), physical vapor deposition (PVD) (sputtering or evaporation), electroplating, electroless plating, stenciling, and screen printing, for example. The RDL 24 can comprise, for example, a foil tape of copper, aluminum or other suitable metal, that can be stamp-cut to provide the desired pattern of traces and ball pads.

The RDL can also comprise a multiple metal layers applied over the insulating film 22 according to known techniques, to form a sandwich or multi-layer under-bump metallurgy (UBM) structure, typically having a tri-metal layer structure. As depicted in **FIG. 9**, for example, the multiple metal layer RDL 24 can comprise overlying layers 36a-36c of a conductive material such as overlying layers of aluminum, nickel, and copper, or overlying layers of chromium, chromium/copper, and copper, for example. Ideally, in utilizing a tri-metal layer structure, the third metal layer 36c is extended to route traces over adjacent units.

As shown in **FIGS. 10-11**, an insulating layer 38 is then applied over the RDL 24 to form a passive exterior layer over the traces 26, 32. The insulating layer 38 can comprise, for example, a polymeric material such as polyimide or another non-conductive elastomer, or a photoimageable polymer such as benzocyclobutene (BCB). The material can be applied

using conventional methods, and the insulating layer 38 can be patterned and etched according to known techniques to provide openings 40 that align with and expose the ball pads 28.

A plurality of ball contacts 30 are attached to the ball pads 28 for connecting the wafer level package 10 as a component to an external circuit board, motherboard or other electrical apparatus or device. Exemplary ball contacts 30 comprise solder typically comprising tin (Sn) and/or lead (Pb), or a conductive material such as a conductive epoxy or conductor-filled epoxy. Solder ball contacts 30 can be formed using conventional processes such as stenciling, screen printing, electroplating, electroless plating, evaporation, and the like. Conductive polymer material can be applied and cured to form the ball contacts.

The wafer can then singulated along scribe lines 16 into individual packages 10, each of which include at least two dies, and shown as four interconnected dies 12a-12d in the illustrated example.

In another embodiment of a wafer level package 10" according to the invention, the package can be fabricated with one or more overlying RDLs to interconnect additional dies within a package, as depicted in **FIGS. 12-17**. By way of example, an initial RDL layer 24" comprising traces 32" interconnecting the bond pads 20a" to 20b" of the first and second dies 12a", 12b", and the bond pads 20c" to 20d" of the third and fourth dies 12c", 12d" can be fabricated as described with respect to the wafer level package 10 of **FIG. 3**. As illustrated in **FIGS. 12-13**, openings 34", 46" are formed through the insulating layer 38", respectively to align with and expose the bond pads 20a"-20d" and ball pads 28" of the initial RDL 24". As depicted in **FIGS. 14-15**, a second RDL 44" can then be applied onto the insulating layer 38", with traces 48" interconnecting the bond pads 20a" to 20c" of the first and third dies 12a", 12c", and the bond pads 20b" to 20d" of the second and fourth dies 12b", 12d", for example. Thus, all dies 12a"-12d" of the wafer level package 10" are interconnected by means of the interconnecting traces 32", 48" of the first and second RDLs 24", 44". As depicted in **FIGS. 16-17**, an insulating layer 50" can then be applied over the RDL 44" to form a passive exterior layer, with openings provided to the balls pads 28", and ball contacts 30" can be connected to the ball pads 28".

Another example of a configuration of a second RDL 44" is illustrated in **FIG. 18**. In the illustrated embodiment of a wafer level package 10"', the initial RDL 24"' is configured similar to the RDL 24 shown in **FIG. 3**. The second RDL 44"' has been fabricated on the insulating layer 38"' such that the traces 32"' interconnect the bond pads 12a"' to the bond pads 12d"' of the first and fourth dies 12a"', 12d"', resulting in the interconnection of all four dies 12a"'-12d"' within the package 10"'. Other configurations of two or more RDLs can be utilized to interconnect two or more dies within a wafer level package.

In yet another embodiment of an integrated wafer level package 10"" according to the invention, the package can comprise two or more redistribution layers (RDLs) whereby the ball pads are fabricated as part of the second (or subsequent) RDL. As depicted in **FIGS. 19-20**, a first RDL 24"" is fabricated on a insulating film 28"". As shown, the RDL 24"" comprises traces 32"" interconnecting the bond pads 20a"" to 20b"" of the first and second dies 12a"", 12b"", and the bond pads 20c"" to 20d"" of the third and fourth dies 12c"", 12d"". An insulating layer 38"" can be applied over the RDL 24"", and openings 34"" formed through the layer to align with and expose the bond pads 20a""-20d"", as illustrated in **FIG. 21-22**. As shown in **FIGS. 23-24**, a second RDL 44"" can then be formed on the insulating layer 38"". The RDL 44"" can comprise traces 48"" interconnecting the bond pads of two dies in the packages, illustrated as connecting bond pads 20b"" to 20c"" of the second and third dies 12b"", 12c"", for example. Other trace connections 48"" can be provided as illustrated, for example, in **FIGS. 14 and 18**.

RDL 44"" further comprises ball pads 56"" that are connected through traces 58"" to bond pads 20a""-20d"" of the dies. As in the other wafer level packages, each bond pad of a die communicates with a ball pad 56"" either directly through a trace 58"", or indirectly through the interconnecting trace 32"" and/or 48"" leading to the bond pad of the adjoining die, which is then connected through the trace 58"" to the ball pad 56"". As depicted in **FIG. 25**, for example, trace 58"" directly connects bond pad 20b"" to the ball pad 56""; and traces 32"", 48"" and/or 58"" indirectly connect bonds pads 20a"", 20c"", and 20d"" to the same ball pad 56"". This results in dies 12a""-12d"" of package 10"" being interconnected to the same ball pad 56"". As depicted in **FIGS. 26-27**, an insulating layer 50"" can then be

applied over the RDL 44"" to form a passive exterior layer, with openings to the ball pads 56"". Ball contacts 30"" can then be connected to the ball pads 56"".

Another embodiment of a wafer level package $10^{v}$ according to the invention is depicted in **FIGS. 28-36**. As illustrated, in **FIGS. 28-29**, initial RDL layer $24^{v}$ is fabricated on an insulating film $22^{v}$ disposed over the dies on the wafer surface, and includes traces $32^{v}$ interconnecting the bond pads $20a^{v}$ to $20b^{v}$ of the first and second dies $12a^{v}$, $12b^{v}$, and the bond pads $20c^{v}$ to $20d^{v}$ of the third and fourth dies $12c^{v}$, $12d^{v}$. As shown in **FIGS. 30-31**, an insulating layer $38^{v}$ is then applied over the RDL $24^{v}$ to form a passive layer over the interconnecting traces $32^{v}$, with openings $60^{v}$ formed between adjoining dies $12a^{v}$, $12b^{v}$ and $12c^{v}$, $12d^{v}$ to expose the interconnecting traces $32^{v}$.

A second insulating layer $62^{v}$ is formed over the insulating layer $38^{v}$ as depicted in **FIGS. 32-33**, and is patterned and etched to provide openings $64^{v}$ and to extend opening $60^{v}$. As shown in **FIG. 32** and in cross-section in **FIG. 34**, a second RDL $44^{v}$ is then applied onto the insulating layer $62^{v}$ to form via interconnects $66^{v}$ within opening $60^{v}$ connected to interconnecting traces $32^{v}$, ball pads $68^{v}$, and traces $70^{v}$ that interconnect the ball pads $68^{v}$ to every other via interconnect $66^{v}$ in a staggered arrangement. As depicted in **FIGS. 35-36**, an insulating layer $50^{v}$ can then be applied over the second RDL $44^{v}$ to form a passive exterior layer, with openings $72^{v}$ to the ball pads $68^{v}$. Ball contacts $30^{v}$ can then be connected to the ball pads $68^{v}$. This arrangement of vias $66^{v}$ and trace connections $70^{v}$ of vias $66^{v}$ to the ball pads $68^{v}$ provides closely matched RDL lengths from the bond pads $20a^{v}$, $20b^{v}$ to the ball pads $68^{v}$.

Referring to **FIG. 2**, the inactive surface 52 of the wafer level package 10 can be covered with a protective dielectric layer 54 such as a photoresist or spun-on polyimide, for example, which can be applied after backgrinding of the wafer or other substrate 14, and prior to singulation. Ideally, the electrical testing and burn-in of the dies is performed before the substrate (wafer) 14 is singulated into individual packages 10. The packaged dies 10 can be severed from the substrate (wafer) 14 singularly or in groups as desired. It is also contemplated that an entire unsevered wafer 14 can be tested and burned-in, and then used as fabricated as a wafer-scale package, particularly for large-capacity memory applications.

The finished wafer level package 10 can be mounted as a component on an end user's printed circuit board or other external electrical apparatus or device via the ball contacts 30 using known techniques.

Two or more wafer level packages 10 can be combined, for example, into an integrated circuit module to enhance or extend the functionality of individual dies. A circuit module can comprise a combination of dies representing a variety of functions or containing the same functionality. Examples of integrated circuit modules include memory modules, device drivers, power modules, communication modems, processor modules and application-specific modules and may include multilayer, multi-chip modules. Examples of multi-chip modules (MCMs) include a single in-line memory module (SIMM), a dual in-line memory module (DIMM), a random access memory (RAM) card or module, and a read-only-memory (ROM) card or module. The circuit module can be a subcomponent of a variety of electronic systems, for example, a personal computer, cellular phone, clock, television, automobile, industrial control system, among others.

**FIG. 37** schematically depicts an embodiment of an integrated circuit module as a multi-chip memory module 74, such as a SIMM or DIMM, which are generally a printed circuit board (PCB) or other support containing a series of memory devices, or a memory card or any other memory die-carrying substrate. A SIMM typically comprises a single inline set of contacts or leads, and a DIMM typically comprises a set of leads on each side of the support with each set representing separate I/O signals. As depicted, the memory module 74 comprises multiple wafer level packages 10 disposed on a support 76, the number of packages 10 depending upon the desired bus width and the desire for parity. Wafer level packages 10 can be disposed on both sides of the support 76. Typically, the memory module 74 accepts a command signal from an external controller (not shown) on a command link 78 and provides for data input and data output on data links 80, both of which are connected to leads 82 extending from the support 76.

In compliance with the statute, the invention has been described in language more or less specific as to structural and methodical features. It is to be understood, however, that the invention is not limited to the specific features shown and described, since the means herein

disclosed comprise preferred forms of putting the invention into effect. The invention is, therefore, claimed in any of its forms or modifications within the proper scope of the appended claims appropriately interpreted in accordance with the doctrine of equivalents.

**WHAT IS CLAIMED:**

1. An integrated wafer level package, comprising:

a plurality of electrically conductive traces on a first insulating film overlying two dies situated on a support substrate, each of the two dies comprising one or more bond pads, and an opening extending through the first insulating film to each of the bond pads; a first trace of said plurality of traces interconnecting one of said one or more bond pads of each of the two dies, and a second insulating layer overlying said first trace, a second trace connecting one of the bond pads of said interconnected bond pads to a ball pad situated on the second insulating film, wherein said interconnected bond pads are connected to a single ball pad.

2. An integrated wafer level package, comprising:

a redistribution layer interconnecting two dies situated on a support substrate, the redistribution layer comprising a first trace situated on a first insulating layer overlying the two dies and connecting a bond pad of each of the two dies, and a second trace and ball pad situated on a second insulating layer overlying said first trace, the second trace connecting said first trace to said ball pad such that said connected bond pads of the two dies are connected to a single ball pad.

3. The package of Claim 2, wherein the second trace is connected to a via interconnect situated in an opening extending through the second insulating layer and in contact with the first trace.

4. An integrated wafer level package, comprising:

at least two semiconductor dies situated on a support substrate, each die comprising a bond pad;

a first insulating film overlying the dies, an opening extending through the first insulating film to each of said bond pads; and

a redistribution layer comprising a plurality of traces on the first insulating film comprising a first trace interconnecting said bond pad of each of a first die and second die, and a second trace connecting said bond pad of the first die or said bond pad of the second die to a ball pad such that said connected bond pads of the first and second dies are connected by

the second trace to a single ball pad, the second trace and the ball pad situated on a second insulating film overlying said first trace.

5. An integrated wafer level package, comprising:

at least two semiconductor dies on a support substrate, each die comprising one or more bond pads;

a first insulating film overlying the dies, an opening extending through the first insulating film to the bond pads; and

a redistribution layer comprising a plurality of traces on the first insulating film comprising a first trace interconnecting one of said one or more bond pads of a first die to one of said one or more bond pads of a second die, and both of the interconnected bond pads of the first and second dies being connected to a single ball pad by a second trace connected to one of said interconnected bond pads, the second trace and the ball pad situated on a second insulating film overlying said first trace.

6. An integrated wafer level package, comprising:

a support substrate comprising two or more semiconductor dies, each die comprising a plurality of bond pads;

a first insulating film over the dies, the film comprising openings aligned with and extending to the bond pads of the dies; and

a plurality of first traces on the first insulating film; one of said first traces connecting one of said plurality of bond pads of a first die to one of said plurality of bond pads of a second die, and a second trace and ball pad on a second insulating film overlying the first traces, said second trace connecting one of the interconnected bond pads to said ball pad, wherein said interconnected bond pads of the first and second dies are connected to a single ball pad.

7. An integrated wafer level package, comprising:

a support substrate comprising two or more semiconductor dies, each die comprising a plurality of bond pads;

a first insulating film over the dies, the film comprising openings aligned with and extending to the bond pads of the dies; and

a plurality of first traces on the first insulating film; one of said first traces connecting one of said plurality of bond pads of each of two dies, and a second trace and ball pad on a second insulating film overlying the first traces, said second trace connecting one of said interconnected bond pads of the two dies to said ball pad, wherein said interconnected bond pads of the two dies are connected to a single ball pad.

8. An integrated wafer level package, comprising:

a support substrate comprising at least first and second semiconductor dies, each die comprising a plurality of bond pads;

a first insulating film over the dies, the film comprising openings aligned with and extending to the bond pads of the dies; and

a plurality of first traces on the first insulating film; whereby one of said first traces connects one of said plurality of bond pads of the second die to one of said plurality of bond pads of the first die, and a second trace and ball pad are situated on a second insulating film overlying said first traces, the second trace connecting one of said bond pads of the first or second die to the ball pad wherein said interconnected bond pads of the first and second dies are connected to a single ball pad.

9. An integrated wafer level package, comprising:

a support substrate comprising at least first and second semiconductor dies, each die comprising a plurality of bond pads;

a first insulating film over the dies, the film comprising openings aligned with and extending to the bond pads of the dies; and

a redistribution layer comprising a plurality of first traces situated on the insulating film, one of the first traces connecting one of said plurality of bond pads of the second die to one of said plurality of bond pads of the first die, and a second trace and ball pad situated on a second insulating film overlying said first traces, the second trace connecting one of said bond pads of the first or second die to the ball pad such that said interconnected bond pads of the first and second dies are connected to a single ball pad.

10. An integrated wafer level package, comprising:

a support substrate comprising at least three semiconductor dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies; and

a plurality of traces and ball pads on the first insulating layer, a bond pad of each of a first die and second die interconnected by a trace, and one of said bond pads of the first and second dies connected by a trace to a ball pad, such that said bond pads of the first and second dies are connected to a single ball pad;

a second insulating layer over the traces; and

a trace on the second insulating layer connecting one of the interconnected bond pads of the first and second dies to a bond pad of a third die, wherein said bond pads of the first, second and third dies are connected to a single ball pad.

11. An integrated wafer level package, comprising:

a support substrate comprising three or more semiconductor dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings exposing the bond pads of the dies;

a plurality of traces and ball pads on the first insulating layer, a bond pad of each of a first die and second die interconnected by a trace, and one of said bond pads of the first and second dies connected by a trace to a ball pad, such that said bond pads of the first and second dies are connected to a single ball pad;

a second insulating layer over the dies with openings to at least one of the interconnected bond pads of the first and second dies and to said connected ball pad, and to a bond pad of the third die; and

a trace on the second insulating layer connecting one of the interconnected bond pads of the first and second dies to a bond pad of a third die.

12. An integrated wafer level package, comprising:

three or more dies on a substrate, each of the dies comprising one or more bond pads;

a first insulating layer over the dies with openings exposing the bond pads of the dies;

a first trace and a second trace formed over the first insulating layer, the first trace interconnecting a bond pad of each of the first and second dies, and a second trace connecting one of said interconnected bond pads of the first and second dies to a ball pad;

a second insulating layer over the first and second traces, the second insulating layer having openings to the bond pads of the three or more dies and the ball pad; and

a third trace on the second insulating layer connecting one of the interconnected bond pads of the first and second dies to a bond pad of the third die;

wherein said bond pads of the first, second and third dies are connected to a single ball pad.

13. An integrated wafer level package, comprising:

a support substrate comprising three or more semiconductor dies, each die comprising one or more bond pads, a bond pad of each of a first die and a second die interconnected by a trace;

an insulating layer over the dies with openings to the bond pads of the dies; and

a plurality of traces on the insulating layer, one of the interconnected bond pads of the first die and the second die connected by a trace to a bond pad of a third die and said bond pads of the first, second and third dies connected to a single ball pad within the package, wherein one of said bond pads of the first, second or third dies is connected by a trace to said ball pad.

14. An integrated wafer level package, comprising:

a support substrate comprising three or more semiconductor dies, each die comprising one or more bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies;

a first redistribution layer comprising traces on the first insulating layer, a bond pad of each of a first die and a second die interconnected by one of said traces;

a second insulating layer over the first redistribution layer with openings to the bond pads of the dies; and

a second redistribution layer on the second insulating layer comprising a ball pad and a trace connecting one of the interconnected bond pads of the first and second dies to a bond

pad of a third die, and a trace connecting said bond pad of the third die to the ball pad, wherein said bond pads of the first, second and third dies are connected to a single ball pad.

15. An integrated wafer level package, comprising:

at least two dies situated on a substrate;

a first insulating layer over the dies with openings to bond pads of the dies;

a first trace on the first insulating layer connecting a bond pad of two of the dies;

an insulating layer over the first trace with an opening to the first trace; and

a ball pad and a second trace over the insulating layer, a via interconnect in the opening in contact with the first trace, and the second trace connecting the via interconnect to the ball pad wherein said bond pads of the two dies are connected to a single ball pad.

16. An integrated wafer level package, comprising:

a support substrate comprising two or more dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings aligned with the bond pads of the dies;

a first trace on the first insulating layer connecting a bond pad of a first die to the bond pad of a second die;

a second insulating layer over the first trace with an opening to the first trace; and

a ball pad and a second trace over the second insulating layer, a via interconnect in the opening in contact with the first trace, and the second trace connecting the via interconnect to the ball pad, wherein said bond pads of the first and second dies are connected to a single ball pad.

17. A semiconductor wafer, comprising: a substrate comprising one or more wafer level packages, each package comprising:

two or more semiconductor dies, and each die comprising a plurality of bond pads;

a first insulating film over the dies with openings extending to the bond pads of the dies;

a plurality of first traces on the first insulating film, one of said plurality of bond pads of each of a first die and a second die within a package interconnected by one of said first traces;

a second insulating film over the first traces; and

a second trace and a ball pad on the second insulating film, one of said interconnected bond pads of the first and second dies connected by the second trace to the ball pad such that said interconnected bond pads of the first and second dies are connected to a single ball pad.

18. A semiconductor wafer, comprising: a substrate comprising a plurality of wafer level packages, each package comprising:

two or more semiconductor dies, and each die comprising a plurality of bond pads;

a first insulating film overlying the dies, openings in said film extending to the bond pads of the dies; and

a redistribution layer comprising a plurality of traces and ball pads comprising a first trace situated on the first insulating film and interconnecting one of said plurality of bond pads of each of a first and second die within each package;

a second insulating film over the first trace; and

a second trace connecting one of said interconnected bond pads of the first and second dies to a ball pad within each package such that said interconnected bond pads of the first and second dies are connected to a single ball pad; the second trace and ball pad situated on the second insulating film.

19. A semiconductor wafer, comprising: a substrate comprising a plurality of wafer level packages, each package comprising:

three or more semiconductor dies, each die comprising a plurality of bond pads;

an insulating film over the dies with openings to the bond pads of the dies;

a first plurality of traces and ball pads on the insulating film, including a trace interconnecting a bond pad of a first die and a bond pad of a second die of at least one package, and a trace connecting one of said interconnected bond pads of the first and second dies to a ball pad within the package;

an insulating layer over the first plurality of traces and ball pads with openings to the bond pads of the dies and to the ball pads; and

a second plurality of traces on the insulating layer, including a trace connecting one of the interconnected bond pads of the first and second dies of the package to a bond pad of a third die of the package such that said bond pads of the first, second and third dies are connected to a single ball pad.

20. A semiconductor wafer, comprising: a plurality of wafer level packages, each package comprising:

four or more semiconductor dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies;

a first set of traces and ball pads on the first insulating layer, including a trace interconnecting a bond pad of each of a first die and a second die of at least one package, a trace connecting one of said interconnected bond pads of the first and second dies to a ball pad within the package such that said bond pads of the first and second dies are connected to a single ball pad, a trace interconnecting a bond pad of each of a third die and a fourth die of the package, and a trace connecting one of said interconnected bond pads of the third and fourth dies to a ball pad within the package;

a second insulating layer over the first set of traces with openings to the bond pads of the dies and the ball pads; and

a second set of traces on the second insulating layer, including a trace connecting one of the interconnected bond pads of the first and second dies to one of the interconnected bond pads of the third and fourth dies within the package, wherein the interconnected bond pads of the dies are connected to a single ball pad.

21. A semiconductor wafer, comprising: a substrate comprising a plurality of wafer level packages, each package comprising:

three or more semiconductor dies, and each die comprising one or more bond pads, a bond pad of each of a first die and a second die interconnected by a trace;

an insulating layer over the trace and comprising openings to the bond pads of the dies; and

a plurality of traces on the insulating layer, including a trace interconnecting one of the interconnected bond pads of the first and second dies of each package to a bond pad of a third die of the package;

wherein one of said bond pads of the first, second or third dies is connected by a trace to a ball pad within the package such that said bond pads of the first, second and third dies are connected to a single ball pad.

22. A semiconductor wafer, comprising: a support substrate comprising a plurality of wafer level packages, each package comprising:

three or more semiconductor dies, each die comprising one or more bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies;

a first redistribution layer on the first insulating layer, a bond pad of each of a first die and a second die of at least one package interconnected by a trace of the first redistribution layer;

a second insulating layer over the first distribution layer with openings to the bond pads of the dies; and

a second redistribution layer comprising traces and one or more ball pads on the insulating layer, one of the interconnected bond pads of the first and second dies connected by a trace of the second redistribution layer to a bond pad of a third die of the package, and said bond pad of the third die connected by a trace of the second redistribution layer to a ball pad such that said bond pads of the first, second and third dies are connected to a single ball pad.

23. A semiconductor wafer, comprising two or more wafer level packages, each package comprising:

two or more dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies;

a plurality of first traces on the first insulating layer, a bond pad of each of a first die and a second die interconnected by a trace;

a second insulating layer over the first traces on an opening to each of the first traces; and

a plurality of ball pads and second traces over the second insulating layer, and a via interconnect in each of the openings, each via interconnect in contact with one of the first traces and connected by one of the second traces to one of the ball pads, such that said interconnected bond pads of the first and second dies are connected to a single ball pad.

24. Any of claims 1-9, further comprising an insulating layer over the first traces.

25. Any of claims 10, 11, 13, 17, 18, 19, 21 and 23, further comprising a second insulating layer overlying the plurality of traces with openings to the ball pads.

26. Either of claims 14 or 22, further comprising a second insulating layer over the second redistribution layer.

27. Any of claims 1-23, further comprising a ball contact mounted on each ball pad.

28. Any of claims 12, 13, 15 and 21, wherein the trace interconnecting the bond pads of the first and second dies is on an insulating film overlying the dies.

29. Any of claims 17-23, further comprising scribe lines between the packages.

30. Any of claims 10, 11, 16, 19 and 23, wherein each package comprises at least four semiconductor dies, and the first plurality of traces comprises a trace interconnecting a bond pad of the fourth die to a bond pad of the third die of each package.

31. Claim 20, wherein the second set of traces comprises a trace connecting a bond pad of the first die to a bond pad of the third or the fourth die of the package.

32. Claim 20, wherein the second set of traces comprises a trace connecting a bond pad of the second die to a bond pad of the third or the fourth die of the package.

33. Claim 20, wherein the second set of traces comprises a trace connecting a bond pad of the first die of the package to a bond pad of the third die of the package, and a trace connecting a bond pad of the second die of the package to a bond pad of a fourth die of the package.

34. An electronic system, comprising: an integrated circuit module comprising at least one wafer level package, the package comprising at least two semiconductor dies on a substrate, each die comprising at least one bond pad, an insulating material overlying the dies, each of the bond pads exposed through openings in the insulating material, and a redistribution layer comprising a plurality of traces and ball pads on the insulating material, a trace interconnecting a bond pad of each of a first die and second die, and a trace connecting either the bond pad of the first die or the bond pad of the second die to a ball pad, wherein the interconnected bond pads of the first and second dies are connected to a single ball pad.

35. A memory module, comprising: a printed circuit board, and an integrated circuit module comprising at least one wafer level package, the package comprising at least two semiconductor dies on a substrate, each die comprising at least one bond pads, an insulating material overlying the dies, each of the bond pads exposed through openings in the insulating material, and a redistribution layer comprising a plurality of traces and ball pads on the insulating material, a trace interconnecting a bond pad of each of a first die and second die, and a trace connecting either the bond pad of the first die or the bond pad of the second die to a ball pad, wherein the interconnected bond pads of the first and second dies are connected to a single ball pad.

36. Claim 34 or 35, wherein the integrated circuit module comprises a multi-chip module.

37. Claim 36, wherein the multi-chip module is selected from the group consisting of a single in-line memory module, a dual in-line memory module, a random access memory card or module, and a read-only-memory card or module.

38. An integrated wafer level package, comprising:

a redistribution layer over and interconnecting two dies on a substrate, the redistribution layer comprising a first trace interconnecting a bond pad of each of the two dies, and a second trace interconnecting one of said bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad.

39. An integrated wafer level package, comprising:

a plurality of electrically conductive traces over and interconnecting two dies on a substrate, a first trace interconnecting a bond pad of each of the two dies, and a second trace connecting one of said bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad.

40. An integrated wafer level package, comprising:

a redistribution layer formed over and interconnecting two dies on a substrate, the redistribution layer comprising a first trace connecting a bond pad of each of the two dies, and a second trace connecting said first trace to a ball pad, wherein said connected bond pads are connected to a single ball pad.

41. A semiconductor wafer, comprising:

one or more wafer level packages formed thereon, each package comprising two or more semiconductor dies, and each die comprising a plurality of bond pads, and a redistribution layer comprising a first plurality of traces and ball pads over the two or more dies wherein a bond pad of each of a first die and a second die within a package are interconnected by a trace, and one of said bond pads of the first and second dies are connected by a trace to a ball pad within the package, wherein said interconnected bond pads are connected to a single ball pad.

42. Any of claims 38-40, wherein the substrate comprises a semiconductor wafer.

43. Any of claims 38-41, further comprising a ball contact mounted on the ball pad.

44. Any of claims 38-41, wherein the dies comprise integrated circuitry to perform a memory function.

45. Any of claims 38-41, further comprising an insulating layer over the traces with openings to the ball pads.

46. Any of claims 38-41, wherein the conductive traces comprise a conductive metal.

47. Claim 46, wherein the conductive metal is selected from the group consisting of copper, aluminum, gold, and nickel.

48. Claim 46, wherein the conductive traces comprise two or more layers of a conductive metal.

49. Claim 46, wherein the conductive traces comprise overlying layers of aluminum, nickel, and copper.

50. Any of claims 38-41, wherein the conductive traces comprise a conductive polymer material.

51. Any of claims 38-40, further comprising an insulating layer over the first trace with an opening to the first trace, with the ball pad and the second trace over the insulating layer, and the second trace connected to a via interconnect in the opening in contact with the first trace.

52. Claim 41, further comprising scribe lines between the packages.

53. Any of claims 38-41, wherein each package comprises at least four semiconductor dies, and the redistribution layer or plurality of traces comprises a trace interconnecting a bond pad of the fourth die to a bond pad of a third die of each package, and a trace connecting one of the interconnected bond pads of the third and fourth dies to one of the interconnected bond pads of the two dies or to the first and second dies.

54. An electronic system, comprising: an integrated circuit module comprising at least one wafer level package comprising a redistribution layer over and interconnecting two dies on a substrate, the redistribution layer comprising a first trace interconnecting a bond pad of each of the two dies, and a second trace interconnecting one of said bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad.

55. A memory module, comprising: a printed circuit board, and an integrated circuit module comprising at least one wafer level package comprising a redistribution layer over and interconnecting two dies on a substrate, the redistribution layer comprising a first trace interconnecting a bond pad of each of the two dies, and a second trace interconnecting one of said bond pads to a ball pad, wherein said bond pads are connected to a single ball pad.

56. Claim 54 or 55, wherein the integrated circuit module comprises a multi-chip module.

57. Claim 56, wherein the multi-chip module is selected from the group consisting of a single in-line memory module, a dual in-line memory module, a random access memory card or module, and a read-only-memory card or module.

58. A method of fabricating a wafer level package, comprising:

applying a first insulating layer over a plurality of semiconductor dies on a substrate, each die comprising one or more bond pads;

forming openings through the first insulating layer to the bond pads of the dies;

forming a redistribution layer over the first insulating layer, the redistribution layer comprising a plurality of traces with a trace interconnecting a bond pad of each of a first die and a second die;

applying a second insulation layer over the redistribution layer; and

forming a trace and ball pad on the second insulation layer, said trace connecting one of the bond pads of the first and second dies to the ball pad, wherein said interconnected bond pads are connected to a single ball pad.

59. A method of fabricating a wafer level package, comprising:

applying a first insulating layer over at least three semiconductor dies on a substrate, each die comprising at least one bond pad;

forming openings through the first insulating layer to the bond pads of the dies; and

forming a first plurality of traces and ball pads on the first insulating layer, wherein a trace interconnects a bond pad of each of a first die and a second die, and a trace connects one of the interconnected bond pads of the first and second dies to a ball pad;

applying a second insulating layer over the traces; and

forming a second plurality of traces over the second insulating layer, wherein a trace on the second insulating layer connects one of the interconnected bond pads of the first and second dies to a bond pad of a third die.

60. A method of fabricating a wafer level package, comprising:

applying an insulating layer over at least three dies on a substrate, each die comprising one or more bond pads, and a trace interconnecting a bond pad of each of a first die and a second die;

forming openings through the insulating layer to the bond pads of the dies; and

forming a plurality of traces and ball pads over the insulating layer, wherein a trace connects one of the interconnected bond pads of the first and second dies to a bond pad of a third die, and a trace connects one of said bond pads of the first, second or third dies to a single ball pad.

61. A method of fabricating a wafer level package, comprising:

forming a first redistribution layer on a first insulating layer over three or more dies on a substrate, each die comprising one or more bond pads, the first insulating layer with openings to the bond pads of the dies, the first redistribution layer comprising a trace interconnecting a bond pad of each of a first die and a second die;

applying a second insulating layer over the first redistribution layer;

forming openings through the second insulating layer to the bond pads of the dies; and

forming a second redistribution layer on the second insulating layer, the second redistribution layer comprising one or more ball pads and a trace connecting one of the

interconnected bond pads of the first and second dies to a bond pad of a third die, and a trace connecting said bond pad of the third die to a ball pad.

62. A method of forming a die package on a wafer level, comprising:

forming a first insulating layer over a wafer having a plurality of dies thereon, the first insulating layer having openings to the bond pads of the dies; and

forming a redistribution layer on the first insulating layer to form a plurality of traces, including a trace connecting a bond pad of each of a first die and a second die;

forming a second insulating layer over the redistribution layer; and

forming a trace and a ball pad on the second insulating layer, said trace connecting one of said interconnected bond pads of the first and second dies to the ball pad such that the interconnected bond pads are connected to a single ball pad.

63. A method of forming a die package, comprising:

forming a first redistribution layer over at least two dies on a substrate, the first redistribution layer comprising a trace interconnecting a bond pad of each of two of said dies;

forming an insulating layer over the first redistribution layer with an opening to expose said trace of the first redistribution layer; and

forming a second redistribution layer over the insulating layer, the second redistribution layer comprising a plurality of ball pads and traces, a via interconnect in the opening of the insulating layer in contact with said trace of the first redistribution layer, and a trace of the second redistribution layer connecting the via interconnect to a ball pad on the insulating layer such that the interconnected bond pads are connected to a single ball pad.

64. Any of Claims 58-63, further comprising applying an insulating layer over the traces on the insulating layer or on the second insulating layer.

65. Claim 64, further comprising forming openings through said insulating layer over the traces to the ball pads.

66. Any of claims 58-63, further comprising: singulating the substrate or wafer to form individual packages, each package comprising the first and second dies with bond pads interconnected by the traces.

67. A method of fabricating an integrated circuit module, comprising:

separating a plurality of wafer level packages to form individual packages, at least one package comprising at least two semiconductor dies, each die comprising at least one bond pad, an insulating material overlying the dies and the bond pads, and a redistribution layer comprising a plurality of traces and ball pads on the insulating material, a trace interconnecting a bond pad of each of a first die and second die, and a trace connecting one of the interconnected bond pads of the first and second dies to a ball pad, wherein the interconnected bond pads are connected to a single ball pad, and

assembling one or more packages into an integrated circuit module.

68. Any of claims 58-63, further comprising mounting a ball contact on the ball pads.

69. A method of fabricating a wafer level package, comprising:

forming a redistribution layer over at least two dies on a substrate, the redistribution layer comprising a plurality of traces and one or more ball pads, a first trace interconnecting a bond pad of each of the two dies, and a second trace connecting one of the interconnected bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad.

70. A method of forming a die package on a wafer level, comprising:

forming a redistribution layer over a plurality of dies on a wafer to form a plurality of ball pads and traces, including a trace interconnecting a bond pad of each of a first die and a second die, and a trace connecting one of said interconnected bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad.

71. Claim 69 or 70, further comprising:

forming an insulating layer over the redistribution layer, the insulating layer having openings to the ball pads of the redistribution layer; and

connecting ball contacts to the ball pads of the redistribution layer.

72. Claim 69 or 70, further comprising:

applying an insulating layer over the redistribution layer;

forming openings through the insulating layer to the ball pads and the bond pads of the dies; and

forming a second redistribution layer on the insulating layer, the second redistribution layer comprising a trace connecting one of the interconnected bond pads of the first and second dies to a bond pad of a third die.

73. A method of fabricating an integrated circuit module, comprising:

separating a plurality of wafer level packages to form individual packages, at least one package comprising a redistribution layer over and interconnecting two dies on a substrate, the redistribution layer comprising a first trace interconnecting a bond pad of each of the two dies, and a second trace connecting one of said interconnected bond pads to a ball pad, wherein said interconnected bond pads are connected to a single ball pad; and

assembling one or more packages into an integrated circuit module.

74. A die package, comprising at least three dies on a substrate, an insulating film over the dies, a bond pad of each of the dies exposed through openings in the insulating film, and a redistribution layer on the insulating film comprising a trace interconnecting the bond pad of each of a first die and a second die and one of said bond pads to a ball pad, and a trace connecting the interconnected bond pad of either the first or second die to a bond pad to a third die.

75. The die package of Claim 74, wherein the substrate comprises a wafer.

76. The die package of Claim 74, wherein at least one die comprises integrated circuitry to perform a memory function.

77. A die package, comprising: at least three dies on a substrate, a first insulating layer over the dies with openings to bond pads of the dies, a trace on the first insulating layer interconnecting the bond pad of each of a first die and second die and connecting one of said interconnected bond pads to a ball pad such that said bond pads are connected to a single ball pad, an insulating layer over the traces, and a trace on the insulating layer connecting one of said interconnected bond pads of the first and second dies to a bond pad of a third die.

78. A die package, comprising at least three dies on a substrate, a first insulating layer over the dies, a first trace on the first insulating layer interconnecting a bond pad of each of a first and second die and connecting one of said bond pads to a single ball pad on the first insulating layer, a second insulating layer over said first trace, a second trace on the second insulating layer connecting one of the interconnected bond pads of the first and second dies to a bond pad of a third die.

79. A die package, comprising at least four dies on a substrate, a first insulating layer over the dies, a first trace on the first insulating layer interconnecting a bond pad of each of a first and second die and connecting one of said bond pads to a single ball pad on the first insulating layer, a second insulating layer over said first trace with openings to the ball pad, to one of the interconnected bond pads of the first and second dies and to a bond pad of a third die, and a second trace on the second insulating layer connecting one of the interconnected bond pads of the first and second dies to the bond pad of the third die.

80. A die package, comprising at least four dies on a substrate, a first insulating layer over the dies with openings to bond pads on said dies, a first trace on the first insulating layer interconnecting a bond pad of each of a first and second die, a second insulating layer over said first trace with openings to the first trace and the bond pad of a third die, a second trace on the second insulating layer connecting the first trace to the bond pad of a third die and to a

ball pad on the second insulating layer, wherein said bond pads of the first, second and third dies are connected to a single ball pad.

81. A die package, comprising at least four dies on a substrate, a first insulating layer over the dies with openings to bond pads on said dies, a first trace on the first insulating layer interconnecting a bond pad of each of a first and second die and a second trace on the first insulating layer interconnecting a bond pad of each of a third and fourth die, a second insulating layer over said first and second traces with an opening to either the first or second trace and to one of the bond pads of the third and fourth die, a third trace on the second insulating layer connecting the first or second trace to the bond pad of the third or fourth die and to a ball pad on the second insulating layer, wherein said interconnected bond pads of the first, second, third and fourth dies are connected to a single ball pad.

82. A die package, comprising at least four dies on a substrate, a first insulating layer over the dies with openings to bond pads on said dies, a first trace on the first insulating layer interconnecting a bond pad of a first die to a second die, a second insulating layer over said first trace with an opening to one of the interconnected bond pads of the first or second die and to a bond pad of a third or fourth die, a second trace on the second insulating layer connecting one of the interconnected bond pads of the first or second die to the bond pad of the third or fourth die, the second trace connected to a ball pad on the second insulating layer, wherein said bond pads of the dies are connected to a single ball pad.

83. A die package, comprising at least four dies on a substrate, a first insulating layer over the dies with openings to bond pads on said dies, a first trace on the first insulating layer interconnecting a bond pad of a first die to a bond pad of a second die, a second insulating layer over said first trace with an opening to the first trace and a bond pad of a third or fourth die, a via interconnect within the opening in contact with the first trace, a second trace on the second insulating layer connecting the via interconnect to the bond pad of the third or fourth die and to a ball pad on the second insulating layer, wherein said bond pads of the dies are connected to a single ball pad.

84. A method of fabricating a die package, comprising:

forming an insulating layer over at least three dies with openings to bond pads on the dies;

forming a first trace and a second trace over the insulating layer, the first trace interconnecting a bond pad of each of the first and second dies, and the second trace connecting one of said interconnected bond pads of the first and second dies to a single ball pad;

forming an insulating layer over the first and second traces, the insulating layer having openings to a bond pad of a third die; and

forming a third trace on the insulating layer to connect one of the interconnected bond pads of the first and second dies to the bond pad of the third die.

85. A method of fabricating a die package, comprising:

forming a first insulating layer over at least four dies with openings to bond pads on the dies;

forming a first set of traces over the first insulating layer, a first trace interconnecting a bond pad of each of a first die and a second die, a second trace connecting one of said interconnected bond pads of the first and second dies to a first ball pad, a third trace interconnecting a bond pad of each of a third die and a fourth die, and a fourth trace connecting one of said interconnected bond pads of the third and fourth dies to a second ball pad;

forming a second insulating layer over the first set of traces with openings to the bond pads of the dies and the ball pads; and

forming a second set of traces on the second insulating layer, with traces connecting one of the interconnected bond pads of the first and second dies to one of the interconnected bond pads of the third and fourth dies.

86. The method of Claim 85, wherein the second set of traces comprises a trace connecting the interconnected bond pad of the first die to the interconnected bond pad of the third or the fourth die of the package.

87. The method of Claim 85, wherein the second set of traces comprises a trace connecting the interconnected bond pad of the second die to the interconnected bond pad of the third or the fourth die of the package.

88. The method of Claim 85, wherein the second set of traces comprises a trace connecting the interconnected bond pad of the first die of the package to the interconnected bond pad of the third die of the package, and a trace connecting the interconnected bond pad of the second die of the package to the interconnected bond pad of a fourth die of the package.

89. A method of fabricating a die package, comprising:

forming a first insulating layer over at least four dies with openings to bond pads on the dies;

forming a first set of traces over the first insulating layer, a first trace interconnecting a bond pad of each of a first die and a second die and connecting one of said interconnected bond pads to a first ball pad, a second trace interconnecting a bond pad of each of a third die and a fourth die and connecting one of said interconnected bond pads to a second ball pad;

forming a second insulating layer over the first set of traces with openings to the bond pads of the dies and the ball pads; and

forming a second set of traces on the second insulating layer with traces connecting the interconnected bond pads of the first and third dies and the interconnected bond pads of the second and fourth dies.

90. A method of fabricating a die package, comprising:

forming a plurality of traces on a first insulating film overlying four or more dies situated on a substrate, each of said dies comprising a bond pad, and each of the bond pads exposed through an opening in the first insulating film, a first trace interconnecting a bond pad of a first and second die and one of said bond pads to a first ball pad, and a second trace interconnecting a bond pad of a third and fourth die and one of said bond pads to a second ball pad;

forming a second insulating film on said dies with openings to said bond pads and ball pads; and

forming a trace on the second insulating film connecting the interconnected bond pad of the first die to one of the interconnected bond pads of the third or fourth die.

91. A semiconductor wafer, comprising:

a plurality of die packages, at least one die package comprising two or more semiconductor dies, each die comprising bond pads, a first insulating layer over the dies with openings to the bond pads, and a redistribution layer comprising a first trace over said first insulating layer interconnecting one of said bond pads of a first die to one of said bond pads of a second die, a second insulating layer over the first trace, and a second trace and a ball pad situated on the second insulating layer, the second trace connecting one of said interconnected bond pads of the first and second dies to the ball pad, wherein said interconnected bond pads of the first and second dies are connected to a single ball pad.

92. A semiconductor wafer, comprising:

a plurality of die packages, each die package comprising two or more semiconductor dies and a first insulating layer over the dies, each die comprising bond pads, and at least one package comprising a first trace situated on the first insulating layer and interconnecting one of said bond pads of each of a first and second die, a second insulating layer over the first trace, and a second trace interconnecting one of said interconnected bond pads of the first and second dies to a ball pad, wherein said interconnected bond pads of the first and second dies are connected to a single ball pad, and the second trace and ball pad are situated on the second insulating layer.

93. A semiconductor wafer, comprising: one or more wafer level packages thereon, at least one package comprising:

two or more semiconductor dies, each die comprising bond pads;

a first insulating layer over the dies with openings to the bond pads; and

a redistribution layer comprising traces and a ball pad, a first trace situated on the first insulating layer, wherein one of said bond pads of each of a first die and a second die are interconnected by said first trace;

a second insulating layer over the first trace; and

a second trace and a ball pad situated on the second insulating layer, wherein one of said interconnected bond pads of the first and second dies is connected by said second trace to said ball pad, and both of said interconnected bond pads of the first and second dies are connected to a single ball pad.

94. A wafer level package, comprising:

a first insulating material overlying first and second dies;

a first trace on the first insulating layer, said first trace interconnecting a bond pad on each of the first and second dies;

a second insulating layer overlying said first trace, and one or more ball pads on said second insulating layer;

a second trace on the second insulating layer connecting one of the interconnected bond pads to one of said ball pads, wherein said interconnected bond pads are not connected to another ball pad.

95. A semiconductor wafer, comprising: a plurality of wafer level packages, each package comprising:

four or more semiconductor dies, each die comprising a plurality of bond pads;

a first insulating layer over the dies with openings to the bond pads of the dies;

a first set of traces and ball pads on the first insulating layer, including a trace interconnecting a bond pad of each of a first die and a second die of at least one package, and a trace interconnecting a bond pad of each of a third die and a fourth die of the package;

a second insulating layer over the first set of traces with openings to the bond pads of the dies and the ball pads; and

a second set of traces on the second insulating layer, including a trace connecting one of the interconnected bond pads of the first and second dies to one of the interconnected bond pads of the third and fourth dies within the package,

and a trace connecting one of the interconnected bond pads of the dies to a ball pad on the second insulating layer such that said interconnected bond pads of the first, second, third and fourth dies are connected to a single ball pad.

96. A die package, comprising: at least three dies on a substrate, a trace interconnecting the bond pad of each of a first die and second die and connecting one of said bond pads to a ball pad such that said bond pads are connected to a single ball pad, an insulating layer over the traces, and a trace on the insulating layer connecting one of said interconnected bond pads of the first and second dies to a bond pad of a third die.

97. A die package, comprising at least four dies on a substrate, a trace interconnecting a bond pad of each of a first and second die and connecting one of said bond pads to a single ball pad, an insulating layer over said first trace with openings to the ball pad, to one of the interconnected bond pads of the first and second dies and to a bond pan of a third die, and second trace on the insulating layer connecting one of the interconnected bond pads of the first and second dies to the bond pad of the third die.

98. A die package, comprising at least four dies on a substrate, a first trace interconnecting a bond pad of each of a first and second die and a second trace interconnecting a bond pad of each of a third and fourth die, an insulating layer over said first and second traces with an opening to either the first or second trace and to one of the bond pads of the third and fourth die, a third trace on the insulating layer connecting the first or second trace to the bond pad of the third or fourth die and to a ball pad on the insulating layer, wherein said interconnected bond pads of the first, second, third and fourth dies are connected to a single ball pad.

99. A method of fabricating a die package, comprising:

forming an insulating layer over at least two dies with openings to bond pads on the dies;

forming a first trace over the insulating layer, the first trace interconnecting a bond pad of two of said dies;

forming an insulating layer over the first trace with an opening exposing the first trace; and

forming a ball pad and a second trace over the insulating layer, and a via interconnect in the opening in contact with the first trace, the second trace connecting the via interconnect to the ball pad.

100. A method of forming a die package on a wafer level, comprising:

forming an insulating layer over at least two dies situated on a wafer with openings to bond pads on the dies;

forming a first redistribution layer over the insulating layer, the first redistribution layer comprising a trace interconnecting a bond pad of each of two of said dies;

forming an insulating layer over the first redistribution layer with openings to expose said trace of the first redistribution layer; and

forming a second redistribution layer over the insulating layer, the second redistribution layer comprising a plurality of ball pads and traces, a via interconnect disposed in each of the openings of the insulating layer in contact with a trace of the first redistribution layer, and a trace of the second redistribution layer connecting the via interconnect to at least one ball pad.

101. A method of fabricating an integrated circuit module, comprising:

forming a plurality of die packages on a substrate, each die package comprising three or more semiconductor dies, a first redistribution layer over a first and second die comprising a trace interconnecting a bond pad of each of said first and second dies, an insulating layer over the first redistribution layer with openings to the bond pads of the three or more dies, and a second redistribution layer on the insulating layer comprising a ball pad and a trace connecting said interconnected bond pad of either the first die or the second die to a bond pad of a third die and a trace connecting said bond pad of the third die to the ball pad;

separating each package on the substrate to form individual packages; and

assembling one or more packages into an integrated circuit module.

102. A method of fabricating an integrated circuit module, comprising:

forming a plurality of die packages on a substrate, each die package comprising three or more semiconductor dies, a first insulating layer over the three or more dies, a first redistribution layer over the first insulating layer comprising a trace interconnecting a bond pad of each of first and second dies, an insulating layer over the first redistribution layer with openings to the bond pads of the three or more dies, and a second redistribution layer on the

second insulating layer comprising a ball pad and a trace connecting said interconnected bond pad of either the first die or the second die to a bond pad of a third die, and a trace connecting said bond pad of the third die to the ball pad;

separating each package on the substrate to form individual packages; and

assembling one or more packages into an integrated circuit module.

103. A method of fabricating an integrated circuit module, comprising:

forming a wafer level package comprising at least two semiconductor dies on a semiconductor wafer, each die comprising at least one bond pad, an insulating layer over the dies, traces and a ball pad over the insulating layer, a bond pad of each of two dies interconnected by a first trace and one of said bond pads of said two dies connected by a second trace to the ball pad;

separating each package on the substrate to form individual packages; and

assembling one or more packages into an integrated circuit module.

104. A method of forming a die package on a wafer level, comprising:

forming a first insulating layer over at least four dies situated on a wafer with openings to bond pads on said dies;

forming a first trace over the first insulating layer interconnecting a bond pad of first and second dies;

forming a second insulating layer over the at least four dies with an opening to expose the interconnected bond pad of the first die and a bond pad of a third die; and

forming a ball pad and a second trace on the second insulating layer and a via interconnect in said opening in contact with the interconnected bond pad of the first die, the second trace connecting the via interconnect to the bond pad of the third die and the ball pad.

105. A method of fabricating an integrated circuit module, comprising:

forming a plurality of die packages on a substrate, each die package comprising at least four dies, a first trace interconnecting a bond pad of first and second dies and a second trace interconnecting a bond pad of third and fourth dies, a first insulating layer over said dies with openings to said interconnected bond pads, a third trace and a ball pad on the first

insulating layer, the third trace connecting one of the interconnected bond pads of the first and second dies to the interconnected bond pad of the third or fourth die and to the ball pad, a second insulating layer over the third trace with an opening to said ball pad, and a contact on said ball pad;

separating each die package to form individual packages; and

assembling one or more of said die packages into an integrated circuit module.

106. The method of Claim 105, wherein the substrate comprises a semiconductor wafer.

107. The method of Claim 105, wherein the integrated circuit module comprises a multi-chip module.

108. The method of Claim 107, wherein the multi-chip module is selected from the group consisting of a single in-line memory module, a dual in-line memory module, a random access memory card or module, and a read-only-memory card or module.

109. A method of fabricating an integrated circuit module, comprising:

forming a plurality of die packages on a substrate, each die package comprising at least four dies, a first insulating layer over said dies, a first trace on the first insulating layer interconnecting a bond pad of first and second dies and a second trace interconnecting a bond pad of third and fourth dies, a second insulating layer over said dies with openings to said interconnected bond pads, a third trace and a ball pad on the second insulating layer, the third trace connecting one of the interconnected bond pads of the first and second dies to the interconnected bond pad of the third or fourth die and to the ball pad, a third insulating layer over the third trace with an opening to said ball pad, and a contact on said ball pad;

separating each die package to form individual packages; and

assembling one or more of said die packages into an integrated circuit module.

110. A method of fabricating an integrated circuit module, comprising:

forming a first insulating layer over at least four dies situated on a substrate with openings to bond pads on said dies;

forming a first trace over the first insulating layer interconnecting a bond pad of a first and second die;

forming a second insulating layer over the at least four dies with an opening to expose at least the interconnected bond pad of the first die and a bond pad of a third die; and

forming a ball pad and a second trace on the second insulating layer and a via interconnect in said opening in contact with the interconnected bond pad of the first die, the second trace connecting the via interconnect to the bond pad of the third die and the ball pad.

111. The method of Claim 110, further comprising:

forming a third insulating layer over the second trace with an opening to said ball pad;

forming a contact on said ball pad;

singulating the at least four dies to form a die package; and

assembling the die package into an integrated circuit module.

112. A method of fabricating an integrated circuit module, comprising:

forming a first insulating layer over at least four dies situated on a substrate with openings to bond pads on said dies;

forming a first trace over the first insulating layer interconnecting a bond pad of a first and second die;

forming a second insulating layer over the at least four dies with an opening to expose the first trace and a bond pad of a third die; and

forming a ball pad and a second trace on the second insulating layer and a via interconnect in said opening in contact with said first trace, the second trace connecting the via interconnect to the bond pad of the third die and the ball pad.

113. The method of Claim 112, wherein at least one die comprises integrated circuitry to perform a memory function.